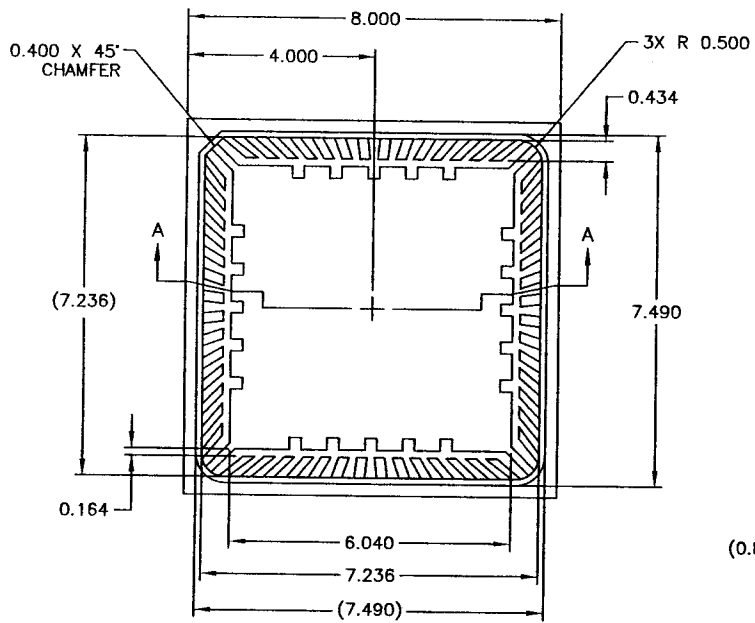
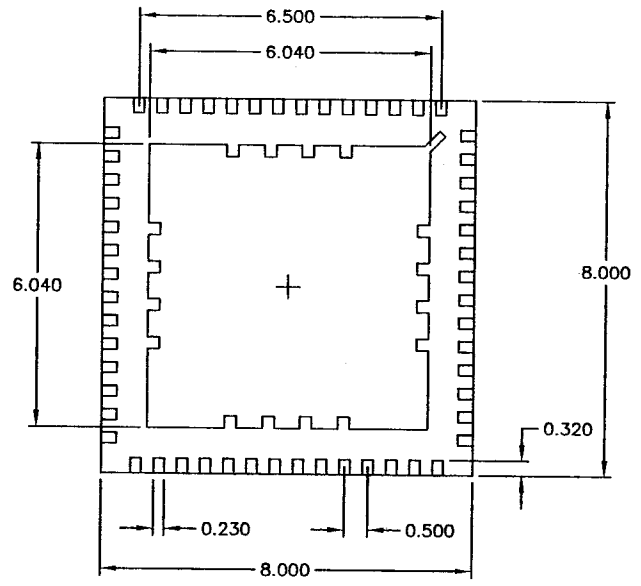
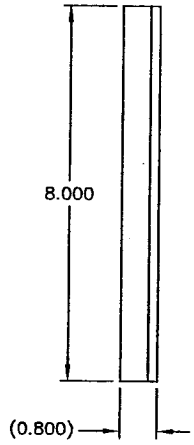


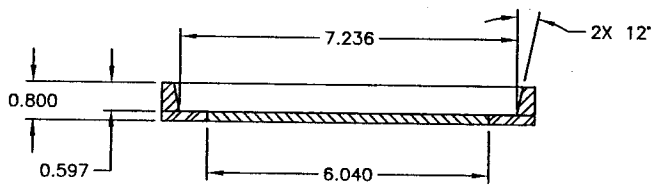
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
		PRODUCTION RELEASE	



TOP VIEW



BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. LEAD THICKNESS: 0.2030 ± 0.0076.
 5. DIE PAD: 6.040 X 6.040.
 6. JEDEC OUTLINE: MO-220 (VLLD-5).

<p>THIRD ANGLE PROJECTION</p>	DRAWN BY	DATE
	APP BY	DATE
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: X.XX ± 0.15 X.XXXX ± --- X.XXX ± 0.100 ANGLES: ± 1°		CUSTOMER
DO NOT SCALE DRAWING		

56 Lead 8mm x 8mm

QFN8X8-056 REV 3